ISTFA 2012, Proceedings from the 38th International Symposium for Testing and Failure Analysis,
November 11-15, 2012
Phoenix, AZ

ISTFA™ 2012

Conference Proceedings from the 38th International Symposium for Testing and Failure Analysis

November 11–15, 2012
Phoenix Convention Center
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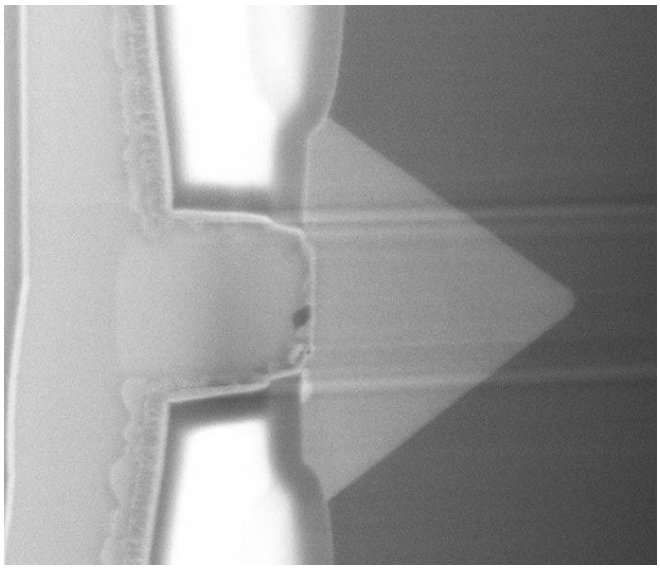

The picture shows an FIB cross section through a defective aluminum contact structure. In the silicon-substrate, under the contact, a perfect geometric shaped material interdiffusion (Al-Si) could be found.

Photo by Susanne Hübner, Fraunhofer Institute for Mechanics of Materials
3rd Place: black and white images
EDFAS 2011 Photo Contest

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Yuk Tsang
Freescale Semiconductor, Austin, Texas, USA

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Stephan Kleindiek
Kleindiek Nanotechnik GmbH, Reutlingen, Germany

Nanoprobe Sample Preparation and Probe Tip Issues
Randal Mulder
Silicon Laboratories, Austin, Texas, USA

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Sean Zumwalt
Multiprobe Inc., Santa Barbara, CA, USA

Contactless Fault Isolation

Moderators
Ed Cole
Sandia National Labs
Frank Altmann
Fraunhofer Institute for Mechanics of Materials)

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Addressing 3D IC Challenges: Magnetic Field Imaging for Non-Destructive 3D Fault Isolation
Antonio Orozco
Neocera, Beltsville, Maryland, USA

The Benefits of Frequency Mapping
Chris Nemirow
DCG Systems, Fremont, California, USA

A New Approach for Short Localization in Thin Dielectrics by Electron Beam Absorbed Current Imaging
Michél Simon-Najasek
Fraunhofer CAM, Halle, Germany

Focused Ion Beam (FIB)

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Jerry Lehman
Zeiss Microscopy, Thornwood, NY, USA

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Drew Erwin
Tescan USA, Pleasanton, California, USA

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Pete Carleson
FEI, Hillsboro, Oregon, USA

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Hideo Tanaka
DCG Systems, Fremont, California, USA

3D FIB/SEM at the 5 nm Voxel Scale for CE and Other IC Applications
Mike Phaneuf
Fibics Incorporated, Ottawa, Ontario, Canada

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Texas Instruments
Jacob Klein
Texas Instruments

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Raymond Mendaros, Analog Devices General Trias (ADGT), Philippines

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Lucille A. Giannuzzi
L.A. Giannuzzi & Associates LLC, Fort Myers, Florida, USA

Safe Removal of WCSP/BGA Devices from Under-Fill Applications
Kristopher Staller
Texas Instruments, Tucson, Arizona, USA

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Scott Silerman, and Robert Chivas
Varioscale, Inc, San Marcos, California, USA

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